



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC117N08NS5	Issued	09. February 2022
MA#	MA005559613		
Package	PG-TDSON-8-45	Weight*	117.98 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.419	0.36	0.36	3555	3555
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	iron	7439-89-6	0.038	0.03		320	
	non noble metal	copper	7440-50-8	37.762	32.01	32.05	320081	320497
wire	noble metal	gold	7440-57-5	0.047	0.04	0.04	401	401
encapsulation	organic material	carbon black	1333-86-4	0.088	0.07		742	
	plastics	epoxy resin	-	6.916	5.86		58619	
	inorganic material	silicondioxide	60676-86-0	36.766	31.16	37.09	311644	371005
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12305	12305
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1403	1403
solder	non noble metal	tin	7440-31-5	0.013	0.01		111	
	noble metal	silver	7440-22-4	0.016	0.01		139	
	non noble metal	lead	7439-92-1	0.626	0.53	0.55	5310	5560
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	iron	7439-89-6	0.022	0.02		189	
	non noble metal	copper	7440-50-8	22.292	18.90	18.93	188951	189197
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			29	
	non noble metal	iron	7439-89-6	0.011	0.01		96	
	non noble metal	copper	7440-50-8	11.320	9.60	9.61	95952	96077
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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